

### THAT 300 Series

#### FEATURES

- 4 Matched NPN Transistors (300)  
4 Matched PNP Transistors (320)  
2 Matched NPNs and PNPs (340)
- Monolithic Construction
- Low Noise
  - $0.75 \text{ nV}/\sqrt{\text{Hz}}$  (PNP)
  - $0.8 \text{ nV}/\sqrt{\text{Hz}}$  (NPN)
- High Speed
  - $f_T = 350 \text{ MHz}$  (NPN)
  - $f_T = 325 \text{ MHz}$  (PNP)
- Excellent Matching – 500  $\mu\text{V}$  typical between devices of same gender
- Dielectrically Isolated for low crosstalk and high DC isolation
- 36V  $V_{\text{CEO}}$

#### APPLICATIONS

- Microphone Preamplifiers
- Current Sources
- Current Mirrors
- Log/Antilog Amplifiers
- Multipliers
- Servos

#### DESCRIPTION

The THAT 300 series are large-geometry, 4-transistor, monolithic NPN and/or PNP arrays exhibiting both high speed and low noise, with excellent parameter matching between transistors of the same gender. With typical base-spreading resistances of 25 ohms for the PNP devices (30 ohms for the NPNs), their resulting low voltage noise of under 1 nV/root-Hz makes the 300 series ideally suited for low-noise amplifier input stages, among other applications.

Fabricated in a dielectrically isolated, complementary bipolar process, each transistor is electrically insulated from the others by a layer of

insulating oxide (not the reverse-biased PN junctions used in conventional arrays) and exhibit inter-device crosstalk and DC isolation similar to that expected from discrete transistors. The resulting low collector-to-substrate capacitance produces a typical NPN  $f_T$  of 350 MHz (325 MHz for the PNPs). Substrate biasing is not required for normal operation, though the substrate should be grounded to optimize speed and minimize crosstalk.

An eight-transistor bare-die array with similar performance characteristics (the THAT 380G) is also available from THAT Corporation. Please contact us directly or through your local distributor for more information.

Part Number	Configuration	Package
THAT300P	4-Matched NPN Transistors	DIP14
THAT300S		SO14
THAT320P	4- Matched PNP Transistors	DIP14
THAT320S		SO14
THAT340P	2 Matched NPN Transistors and 2 Matched PNP Transistors	DIP14
THAT340S		SO14

Table 1. Ordering Info

## SPECIFICATIONS<sup>1</sup>

<b>Maximum Ratings (<math>T_A = 25^\circ\text{C}</math>)</b>						
Parameter	Symbol	Conditions	Min	Typ	Max	Units
NPN Collector-Emitter Voltage	$BV_{CEO}$	$I_C = 1 \text{ mAdc}, I_B = 0$	36	40	—	V
NPN Collector-Base Voltage	$BV_{CBO}$	$I_C = 10 \text{ }\mu\text{Adc}, I_E = 0$	36	40	—	V
NPN Emitter-Base Voltage	$BV_{EBO}$	$I_E = 100 \text{ }\mu\text{Adc}, I_C = 0$	5	—	—	V
NPN Collector Current	$I_{C \text{ MAX}}$		10	20		mA
NPN Emitter Current	$I_{E \text{ MAX}}$		10	20		mA
PNP Collector-Emitter Voltage	$BV_{CEO}$	$I_C = 1 \text{ mAdc}, I_B = 0$	-36	-40	—	V
PNP Collector-Base Voltage	$BV_{CBO}$	$I_C = 10 \text{ }\mu\text{Adc}, I_E = 0$	-36	-40	—	V
PNP Emitter-Base Voltage	$BV_{EBO}$	$I_E = 100 \text{ }\mu\text{Adc}, I_C = 0$	-5	—	—	V
PNP Collector Current	$I_{C \text{ MAX}}$		-10	-20		mA
PNP Emitter Current	$I_{E \text{ MAX}}$		-10	-20		mA
Collector-Collector Voltage	$BV_{CC}$		$\pm 100$	$\pm 200$	—	V
Emitter-Emitter Voltage	$BV_{EE}$		$\pm 100$	$\pm 200$	—	V
Operating Temperature Range	$T_A$		0		70	$^\circ\text{C}$
Maximum Junction Temperature	$T_{J \text{ MAX}}$				150	$^\circ\text{C}$
Storage Temperature	$T_{\text{STORE}}$		-45		125	$^\circ\text{C}$

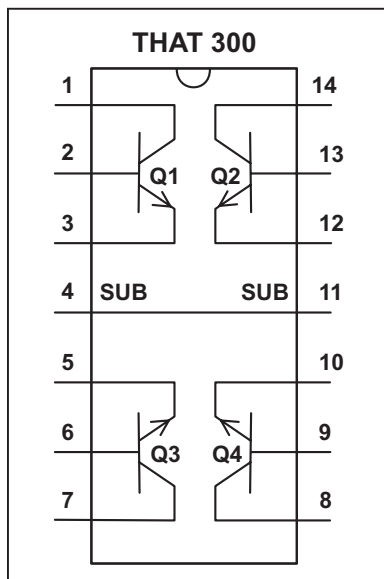


Fig 1. 300 Pinout

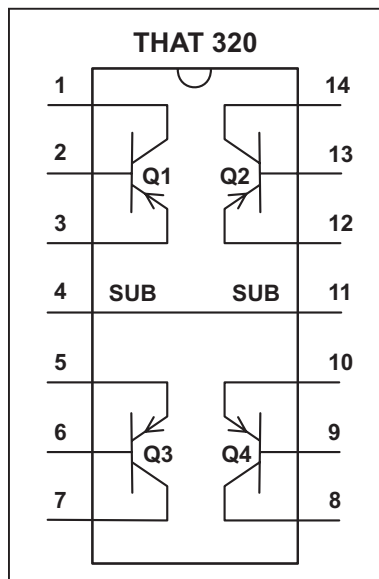


Fig 2. 320 Pinout

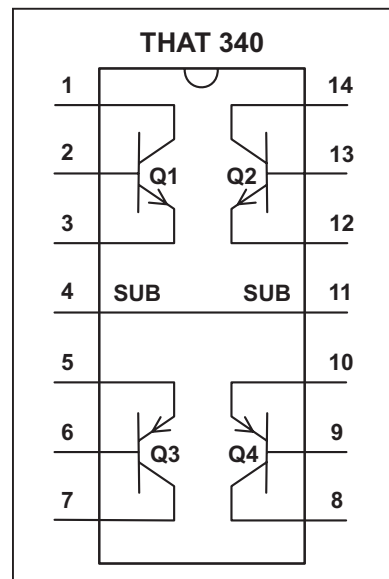


Fig 3. 340 Pinout

## SPECIFICATIONS<sup>1</sup> (Cont'd)

<b><u>NPN Electrical Characteristics<sup>2</sup></u></b>						
Parameter	Symbol	Conditions	Min	Typ	Max	Units
NPN Current Gain	$h_{fe}$	$V_{CB} = 10\text{ V}$ $I_C = 1\text{ mA}$ $I_C = 10\text{ }\mu\text{A}$	60	100 100	— —	
NPN Current Gain Matching	$\Delta h_{fe}$	$V_{CB} = 10\text{ V}, I_C = 1\text{ mA}$	—	5	—	%
NPN Noise Voltage Density	$e_N$	$V_{CB} = 10\text{ V}, I_C = 1\text{ mA}, 1\text{ kHz}$	—	0.8	—	$\text{nV}/\sqrt{\text{Hz}}$
NPN Gain-Bandwidth Product	$f_T$	$I_C = 1\text{ mA}, V_{CB} = 10\text{ V}$		350		MHz
NPN $\Delta V_{BE}$ (THAT300: $V_{BE1}-V_{BE2}; V_{BE3}-V_{BE4}$ ) (THAT340: $V_{BE1}-V_{BE2}$ )	$V_{OS}$	$I_C = 1\text{ mA}$ $I_C = 10\text{ }\mu\text{A}$	— —	$\pm 0.5$ $\pm 0.5$	$\pm 3$	mV mV
NPN $\Delta I_B$ (THAT300: $I_{B1}-I_{B2}, I_{B3}-I_{B4}$ ) (THAT340: $I_{B1}-I_{B2}$ )	$I_{OS}$	$I_C = 1\text{ mA}$ $I_C = 10\text{ }\mu\text{A}$	— —	$\pm 500$ $\pm 5$	$\pm 1500$	nA nA
NPN Collector-Base Leakage Current	$I_{CBO}$	$V_{CB} = 25\text{ V}$	—	25	—	pA
NPN Bulk Resistance	$r_{BE}$	$V_{CB} = 0\text{ V}, 10\text{ }\mu\text{A} < I_C < 10\text{ mA}$	—	2	—	$\Omega$
NPN Base Spreading Resistance	$r_{bb}$	$V_{CB} = 10\text{ V}, I_C = 1\text{ mA}$	—	30	—	$\Omega$
NPN Collector Saturation Voltage	$V_{CE(SAT)}$	$I_C = 1\text{ mA}, I_B = 100\text{ }\mu\text{A}$	—	0.05		V
NPN Output Capacitance	$C_{OB}$	$V_{CB} = 10\text{ V}, I_E = 0\text{ mA}, 100\text{ kHz}$		3		pF
NPN Collector-Collector Capacitance (THAT300: Q1-Q2, Q3-Q4) (THAT340: Q1-Q2)	$C_{CC}$	$V_{CC} = 0\text{ V}, 100\text{ kHz}$		0.7		pF

<b><u>PNP Electrical Characteristics<sup>2</sup></u></b>						
Parameter	Symbol	Conditions	Min	Typ	Max	Units
PNP Current Gain	$h_{fe}$	$V_{CB} = 10\text{ V}$ $I_C = 1\text{ mA}$ $I_C = 10\text{ }\mu\text{A}$	50	75 75	— —	
PNP Current Gain Matching	$\Delta h_{fe}$	$V_{CB} = 10\text{ V}, I_C = 1\text{ mA}$	—	5	—	%
PNP Noise Voltage Density	$e_N$	$V_{CB} = 10\text{ V}, I_C = 1\text{ mA}, 1\text{ kHz}$	—	0.75	—	$\text{nV}/\sqrt{\text{Hz}}$
PNP Gain-Bandwidth Product	$f_T$	$I_C = 1\text{ mA}, V_{CB} = 10\text{ V}$		325		MHz
PNP $\Delta V_{BE}$ (THAT320: $V_{BE1}-V_{BE2}; V_{BE3}-V_{BE4}$ ) (THAT340: $V_{BE3}-V_{BE4}$ )	$V_{OS}$	$I_C = 1\text{ mA}$ $I_C = 10\text{ }\mu\text{A}$	— —	$\pm 0.5$ $\pm 0.5$	$\pm 3$	mV mV
PNP $\Delta I_B$ (THAT320: $I_{B1}-I_{B2}, I_{B3}-I_{B4}$ ) (THAT340: $I_{B3}-I_{B4}$ )	$I_{OS}$	$I_C = 1\text{ mA}$ $I_C = 10\text{ }\mu\text{A}$	— —	$\pm 700$ $\pm 7$	$\pm 1800$	nA nA
PNP Collector-Base Leakage Current	$I_{CBO}$	$V_{CB} = 25\text{ V}$	—	-25	—	pA

1. All specifications subject to change without notice.
2. Unless otherwise noted,  $T_A = 25^\circ\text{C}$ .

**SPECIFICATIONS<sup>1</sup> (Cont'd)**

PNP Bulk Resistance	$r_{BE}$	$V_{CB} = 0 \text{ V}, 10\mu\text{A} < I_C < 10 \text{ mA}$	—	2	—	$\Omega$
PNP Base Spreading Resistance	$r_{bb}$	$V_{CB} = 10 \text{ V}, I_C = 1 \text{ mA}$	—	25	—	$\Omega$
PNP Collector Saturation Voltage	$V_{CE(SAT)}$	$I_C = 1 \text{ mA}, I_B = 100 \mu\text{A}$	—	-0.05		V
PNP Output Capacitance	$C_{OB}$	$V_{CB} = 10 \text{ V}, I_E = 0 \text{ mA}, 100 \text{ kHz}$		3		pF
PNP Collector-Collector Capacitance (THAT320: Q1-Q2; Q3-Q4) (THAT340: Q3-Q4)	$C_{CC}$	$V_{CC} = 0 \text{ V}, 100 \text{ kHz}$		0.6		pF

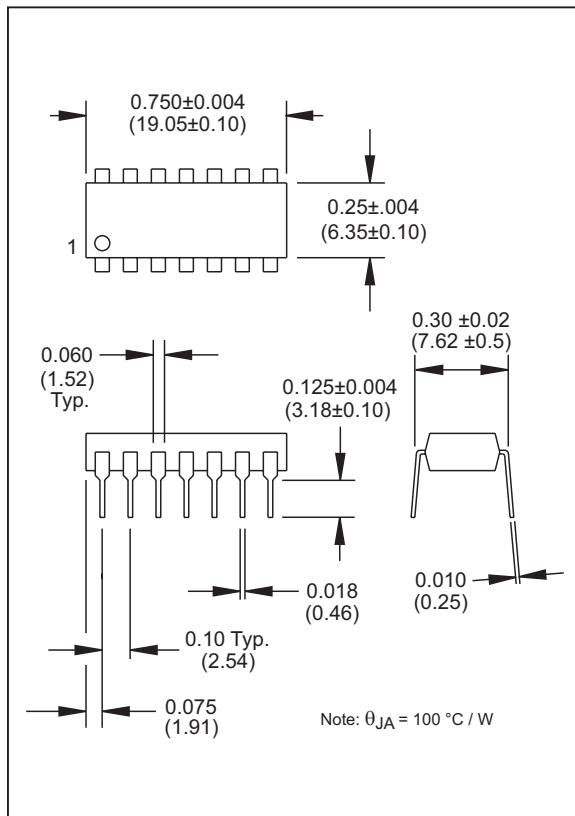


Figure 4. Dual-In-Line Package Outline

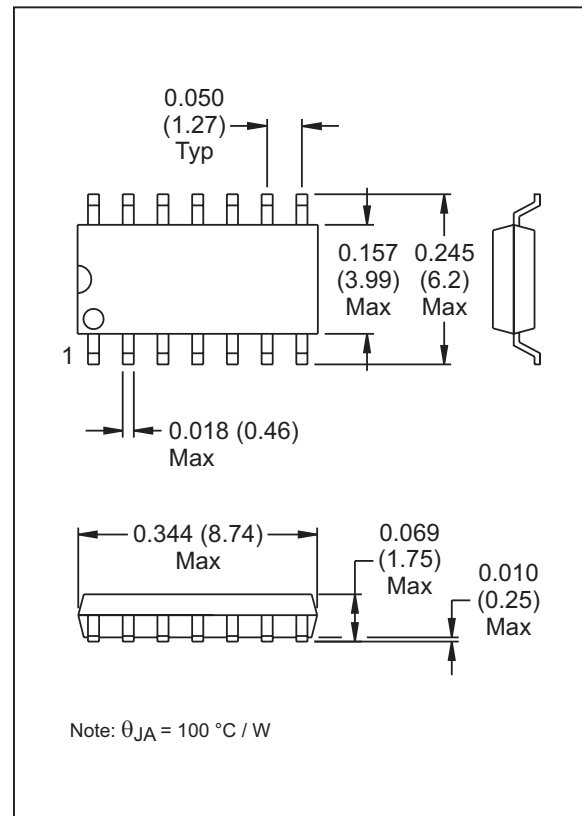


Figure 5. Surface-Mount Package Outline

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**CAUTION: THIS IS AN ESD (ELECTROSTATIC DISCHARGE) SENSITIVE DEVICE.**

It can be damaged by the currents generated by electrostatic discharge. Static charge and therefore dangerous voltages can accumulate and discharge without detection causing a loss of function or performance to occur.

The transistors in this device are unprotected in order to maximize performance and flexibility. They are more sensitive to ESD damage than many other ICs which include protection devices at their inputs. Note that all of the pins (not just the "inputs") are susceptible.

Use ESD preventative measures when storing and handling this device. Unused devices should be stored in conductive packaging. Packaging should be discharged to the destination socket before the devices are removed. ESD damage can occur to these devices even after they are installed in a board-level assembly. Circuits should include specific and appropriate ESD protection.